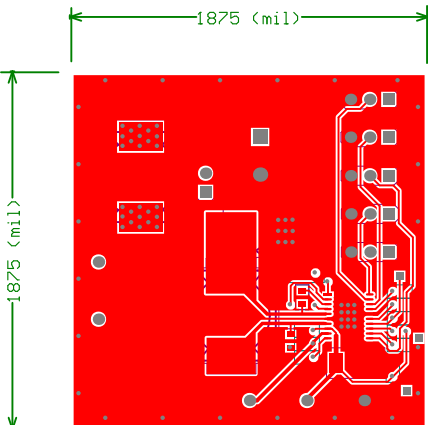


FABRICATION CHART				
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☐ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	

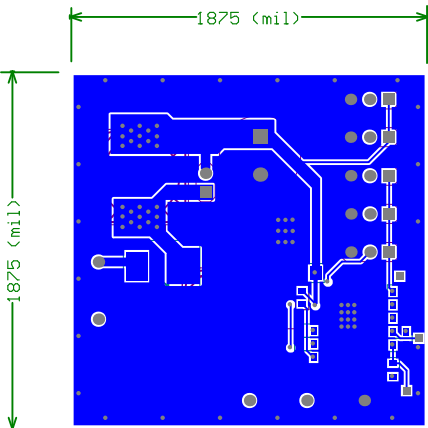


TEXAS INSTRUMENTS		
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NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:** ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
- BASE LAMINATE:** PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
- SOLDERMASK:** SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
- PLATING:** HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
- FINISH:** PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN. ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
- LEGEND:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
- MARKINGS:** BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
- WORKMANSHIP:** BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
- DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
- PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
- PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

FABRICATION CHART				
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☐ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	



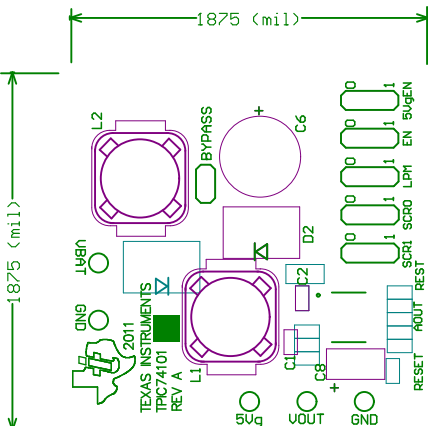
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2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
4. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
5. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN. ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
6. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
7. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
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FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☐ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	

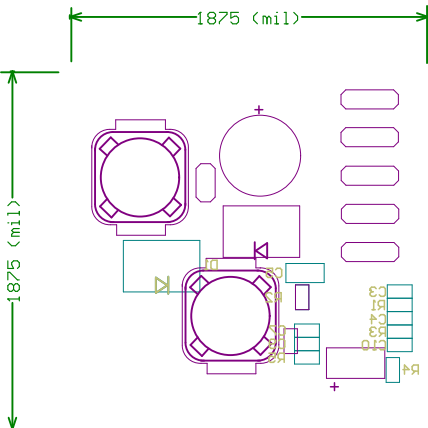


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3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
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5. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN. ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
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FABRICATION CHART				
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☐ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	



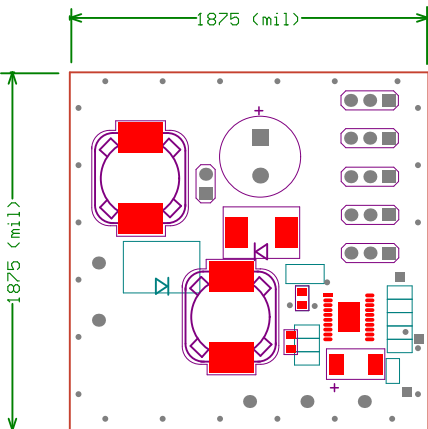
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- FINISH:** PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN. ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
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FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☐ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	

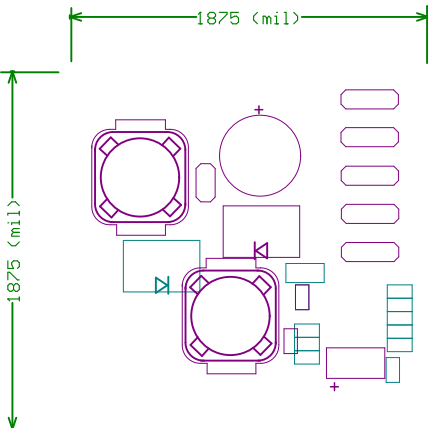


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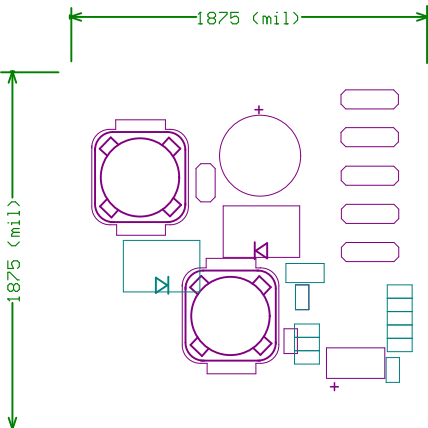


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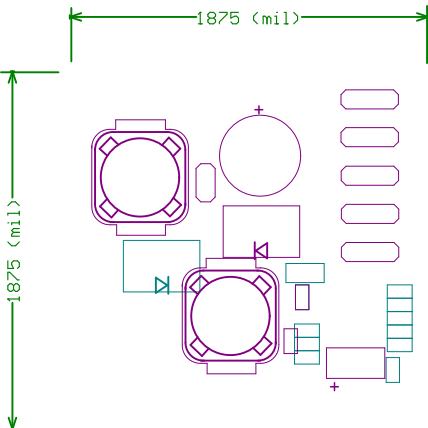


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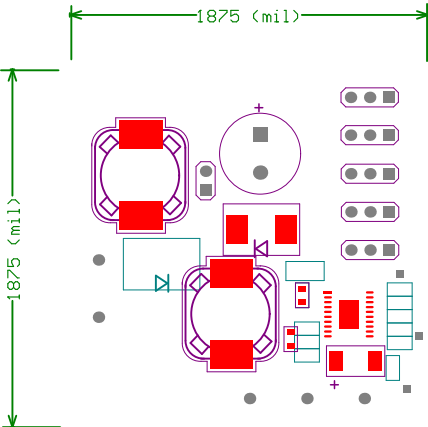
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- 9. DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- 10. DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
- 11. PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
- 12. PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☐ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	



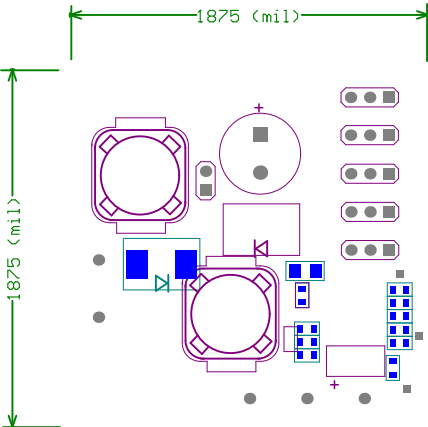
TEXAS INSTRUMENTS		
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Date: 08/05/11	Filename:	

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
4. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
5. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN. ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
6. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
7. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
8. WORKMANSHIP: BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
9. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
10. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
11. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
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FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☐ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	



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2. BASE LAMINATE:

PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK:

SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
4. PLATING:

HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
5. FINISH:

PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN. ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
6. LEGEND:

IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
7. MARKINGS:

BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
8. WORKMANSHIP:

BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
9. DOCUMENTATION:

PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
10. DRILL SIZES:

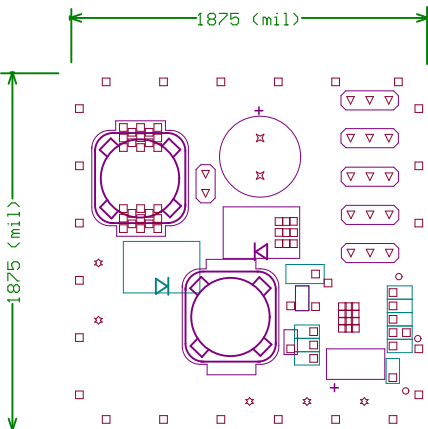
HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
11. PANEL BORDER:

ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
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FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
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DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	

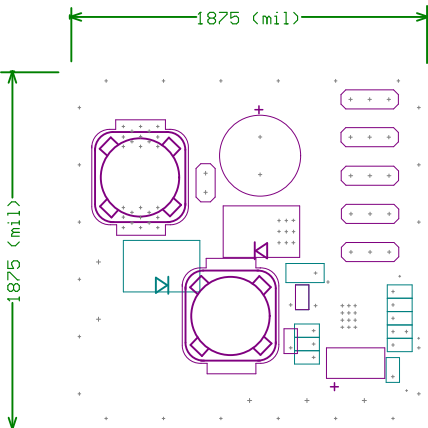


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DESIGN	TRACE/GAP SPACING	LAYER COUNT		
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006	☐ SINGLE SIDED ☐ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☒ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER	



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Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have **not** been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

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